



Material Content Data Sheet



Sales Product Name		BTM7750G		Issued		27. July 2015		
MA#		MA001364432						
Package		PG-DSO-28-22		Weight*		810.67 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	11.958	1.48	1.48	14750	14750
leadframe	inorganic material	phosphorus	7723-14-0	0.072	0.01		89	
	non noble metal	zinc	7440-66-6	0.288	0.04		355	
	non noble metal	iron	7439-89-6	5.754	0.71		7098	
wire	non noble metal	copper	7440-50-8	233.637	28.82	29.58	288202	295744
	non noble metal	aluminium	7429-90-5	1.651	0.20	0.20	2037	2037
	encapsulation	organic material	carbon black	1333-86-4	1.097	0.14		1353
encapsulation	plastics	epoxy resin	-	78.416	9.67		96730	
	inorganic material	silicondioxide	60676-86-0	468.852	57.83	67.64	578352	676435
leadfinish	non noble metal	tin	7440-31-5	4.975	0.61	0.61	6136	6136
plating	noble metal	silver	7440-22-4	0.678	0.08	0.08	836	836
glue	plastics	epoxy resin	-	0.576	0.07		711	
	noble metal	silver	7440-22-4	2.716	0.34	0.41	3351	4062
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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